

REMARKS

Applicants cancel non-elected claims 18-41 without disclaimer and without prejudice to the filing of a divisional application directed to these canceled claims. Applicants add new claims 42-45; therefore, claims 1-17 and 42-45 are now under consideration in this application.

Applicants amend claim 1 more clearly to define the features of the embodiment of the invention as recited therein. Applicants submit that this amendment is merely for clarification purposes and as such does not narrow the scope of the original claim 1.

Applicants add dependent claims 42-44 and an independent claim 45 to more fully cover within the claims various aspects of Applicants' invention as described in Applicants' specification (see, for example, page 12, lines 6-12).

As a formal matter, the Examiner indicates that the Japanese Patent No. 2679681 submitted with the IDS filed September 7, 2001 has not been considered, allegedly because the concise explanation requirement has not been met for this Japanese language reference. However, as noted in the IDS Submission dated September 7, 2001, this reference corresponds to Japanese Laid-Open Patent Application No. 8-306820 for which an English language Abstract has been provided with the September 7, 2001 submission. Therefore, Applicants respectfully request the Examiner to consider this reference, and to return an initialed Form PTO-1449 accordingly.

The Examiner rejects claims 1-3, 5-8 and 15-17 under 35 U.S.C. § 103(a) as unpatentable over Baba in view Suzuki et al. (Suzuki). The Examiner indicates that **claims 4 and 9-14 would be allowable** if rewritten in independent form including all of the limitations of the base claim.

Applicants respectfully traverse the Examiner's prior art rejection as follows.

Applicants' invention provides a semiconductor package board having a unique combination of features, including, *inter alia*, a multilayer wiring film having a first surface in contact with a metal base plate, the first surface having a plurality of first metal pads in a region exposed by an opening in the metal base plate.

Contrary to the Examiner' analysis, Baba does not disclose, teach or suggest such a feature. In particular, Baba discloses package construction for a semiconductor device which includes lines 9 provided on BGA substrate 1, and solder bumps 5 provided for joining "an external electrode of the semiconductor chip 2 to an electrode on the surface of the BGA substrate 1" (see Baba, col. 4, lines 7-65, and Figs. 1 and 2). Nowhere does Baba disclose, teach or suggest that its electrodes on the surface of the BGA substrate 1 have metal pads. Instead, Baba provides solder bumps 5 which electrically connect to the external electrodes (not illustrated) of a plurality of lines on the BGA substrate (see Baba, Fig. 2; see also Baba, col. 6, lines 1-13 and solder bumps 5a and 5b in Figs. 3(a)).

On the other hand, Suzuki is directed to the structure of the metal base substrate, and is completely silent on the details of the structure of the wiring on a BGA substrate. Thus, Suzuki is incapable of supplying the above-noted deficiency of Baba.

Accordingly, Applicants' independent claim 1, as well as its dependent claims 2, 3, 5-8 and 15-17 (which incorporate all the novel and unobvious features of their base claim), would not have been obvious from any reasonable combination of Baba and Suzuki.

In view of the above, reconsideration and allowance of this application are now believed to be in order, and such actions are hereby solicited. If any points remain in issue which the

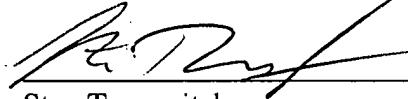
Amendment Under 37 C.F.R. § 1.111
U.S. Appln No. 09/894,123

Atty Dkt No. Q65269

Examiner feels may be best resolved through a personal or telephone interview, the Examiner is kindly requested to contact the undersigned attorney at the telephone number listed below.

The USPTO is directed and authorized to charge all required fees, except for the Issue Fee and the Publication Fee, to Deposit Account No. 19-4880. Please also credit any overpayments to said Deposit Account.

Respectfully submitted,



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PATENT TRADEMARK OFFICE

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APPENDIX
VERSION WITH MARKINGS TO SHOW CHANGES MADE

IN THE CLAIMS:

The claims are amended as follows:

1. (Amended) A semiconductor package board comprising:
a metal base plate having an opening suited for receiving therein a semiconductor chip;
and
a multilayer wiring film formed on said metal base plate,
said multilayer wiring film having a first surface in contact with said metal base plate,
[and mounting thereon] said first surface having a plurality of first metal pads [within] in a
region of said first surface exposed [from] by said opening [of] in said metal base plate.

Claims 42-45 are added as new claims.

Claims 18-41 are canceled.